

Presentation on Si-Ge needs for high quality amplifier

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Why SiGe?

Due to booming market for computer and wireless communication systems, there is a need of a single transistor technology simultaneously capable of delivering:

- Low Power
- High Linearity
- Ultra Low Noise
- High speed of operation for RF, analog, memory and digital circuits
- Low cost

“One technology fits all”

Moreover, this technology has:

- High Reliability
- Radiation hardness
- Easy integration
- An active developers community

All these are the main requirements for present and future high energy and nuclear physics instrumentation!

Si BJT vs SiGe HBT

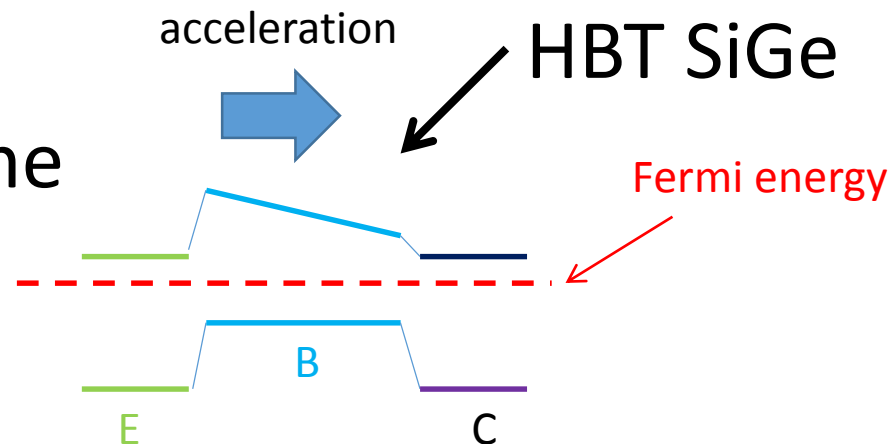
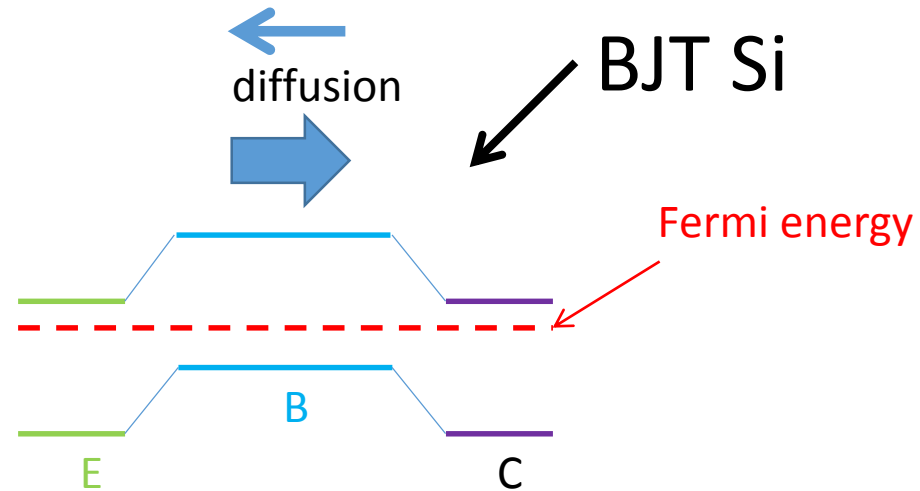
BJT performances

- $\beta = \tau_c / \tau_t$
- $f_t = 1 / \tau_t$
- $N = K * \tau_t$

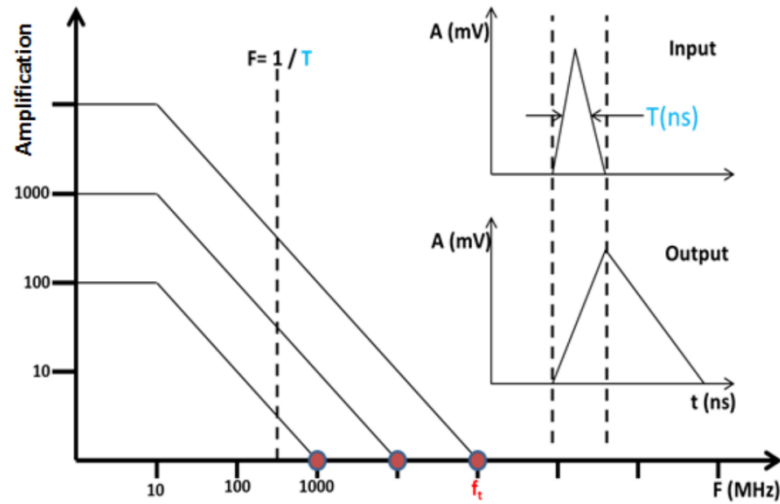
τ_c = base life time

τ_t = base transient time

$\tau_t(\text{Si}) \gg \tau_t(\text{SiGe})$

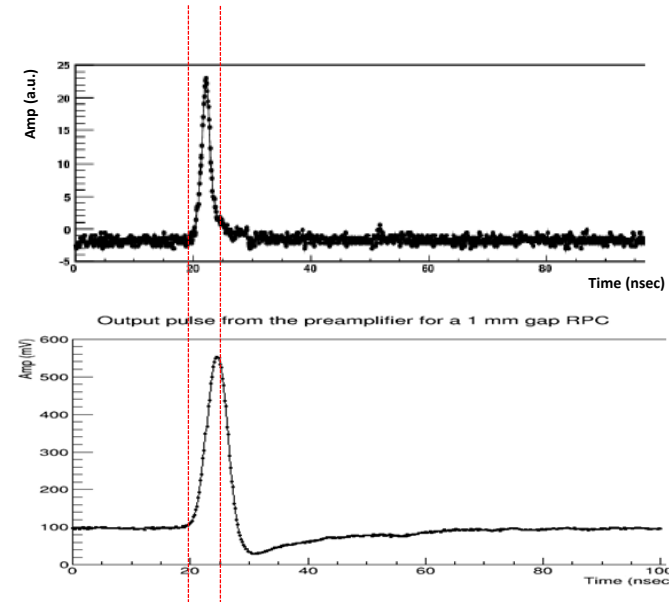


Strategy for the new front-end (SiGe)

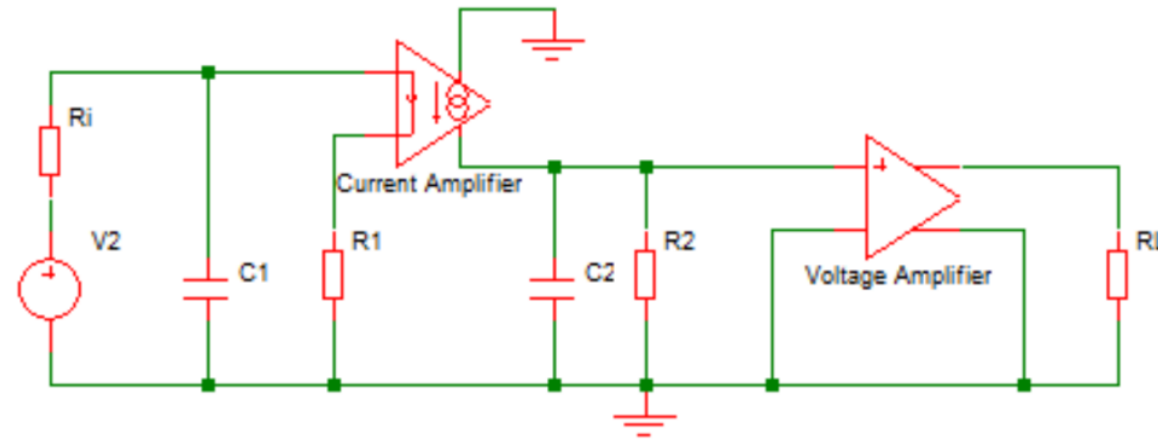


Working strategy

Actual result for
the RPC signal



The block diagram of the preamplifier



The same scheme can be used for both Silicon and SiGe technology for a comparison.





Silicon technology

Voltage supply	3–5 Volt
Sensitivity	2–4 mV/fC
Noise (independent from detector)	4000 e ⁻ RMS
Input impedance	100–50 Ohm
B.W.	10–100 MHz
Power consumption	10 mW/ch
Rise time $\delta(t)$ input	300–600 ps
Radiation hardness	1 Mrad, 10 ¹³ n cm ⁻²





SiGe technology

Voltage supply	2–3 Volt
Sensitivity	2–6 mV/fC
Noise (independent from detector)	500 e ⁻ RMS
Input impedance	50–200 Ohm
B.W.	30–100 MHz
Power consumption	2 mW/ch
Rise time $\delta(t)$ input	100–300 ps
Radiation hardness [4]	50 Mrad, 10 ¹⁵ n cm ⁻²

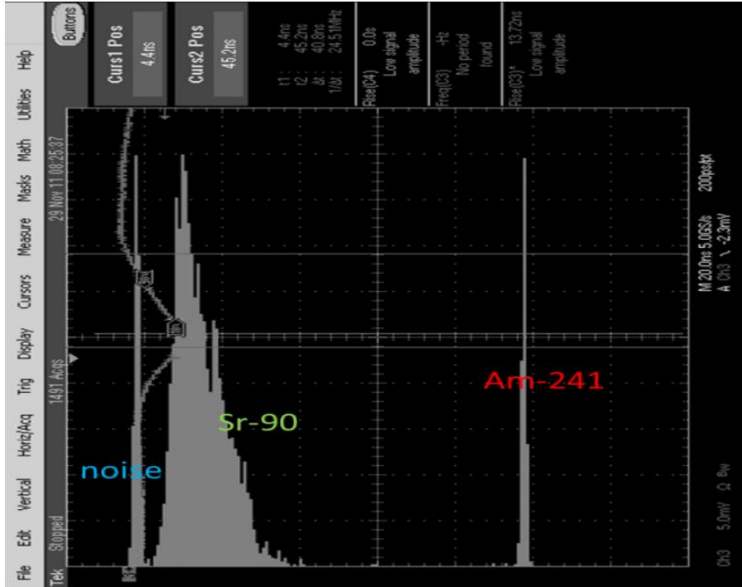
Problems solved by this amplifier

- Signal **pile up** at high rate  **small integration time** (10 ns) with low noise ($500e^-$ RMS).
- Uncorrelated **background**  suppressed through **fast rise time** (100 ps).
- Detectors with large **pick-up capacitance**  the noise of the preamplifier is **500 e^- RMS up to 1 nF.**
- **Thickness reduction** for Silicon and Diamond detectors.  **Small noise** (down to $200 e^-$) for small collected charge.

Problems solved by this amplifier

- **High density** of read out channels  **Low power consumption** (down to 1.5 V power supply).
- Fluctuations of **picked-up charge**  **large dynamics** (ex: space resolution with charge centroid).
- **Rate capability** and **ageing** of the detectors  amplification transferred **from the detector to the front end electronics**.
- Radiation and temperature **damage to the electronics**  possibility to **interconnect the preamplifier to the detector via a coaxial cable** (up to 50 m). (Tokamak, nuclear reactors and accelerators).

Preliminary results with SiGe amplifier on a diamond detector.



Histogram with:

- Noise of the SiGe amplifier
- Spectrum of a beta source (^{90}Sr)
- Spectrum of an alpha source (^{241}Am)

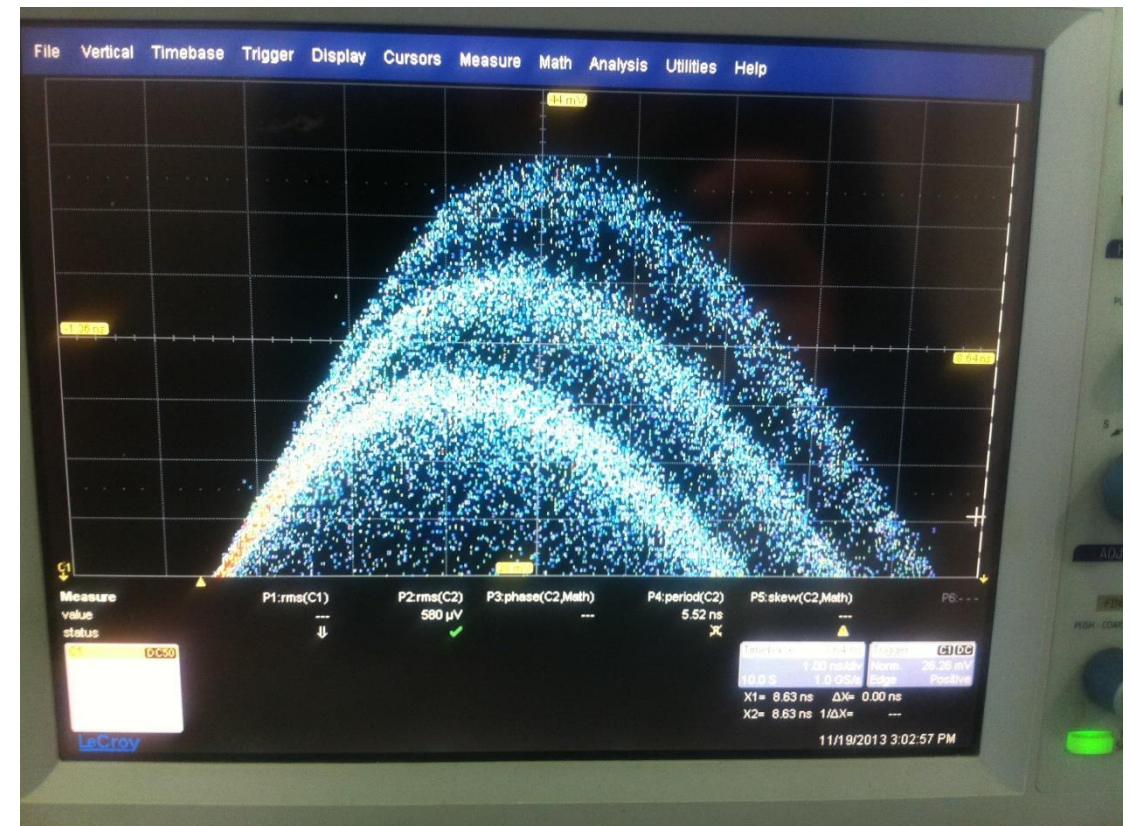
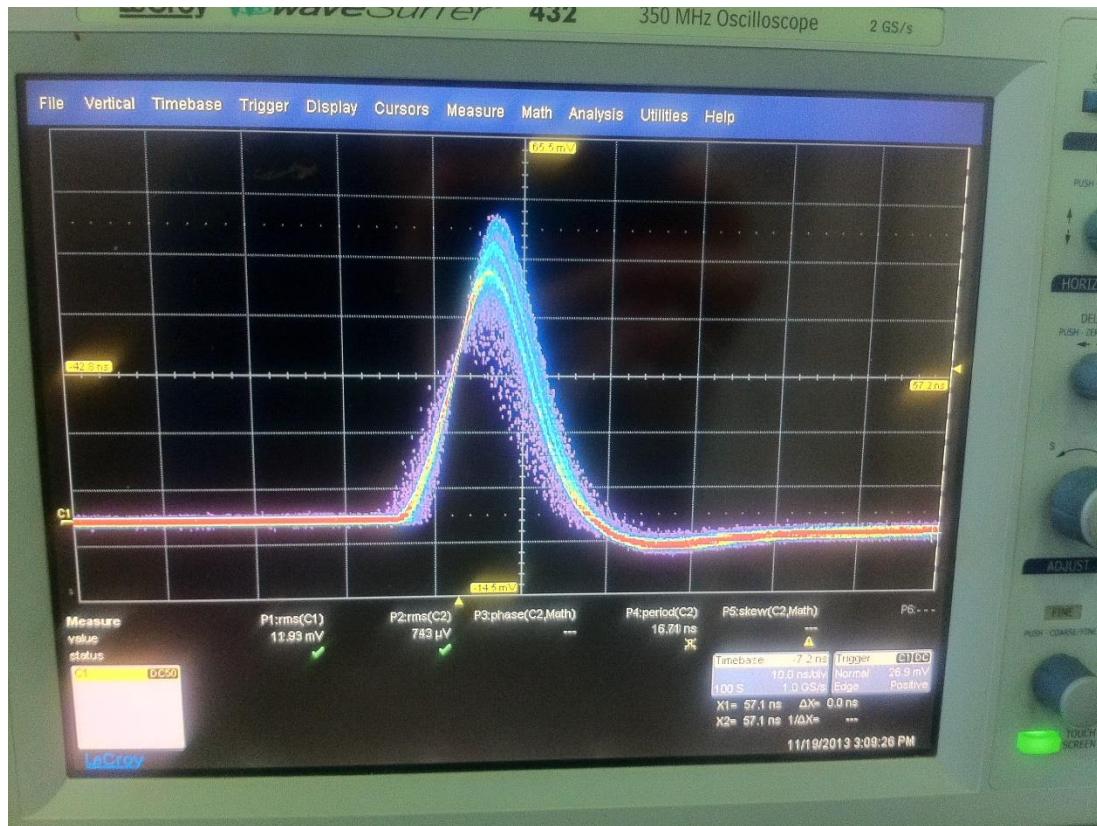
Detected by a CVD (0.5mm thickness)

Example of pulse from a minimum ionizing particle on a CVD (0.5mm thickness).
~8000 e^- input to the amplifier



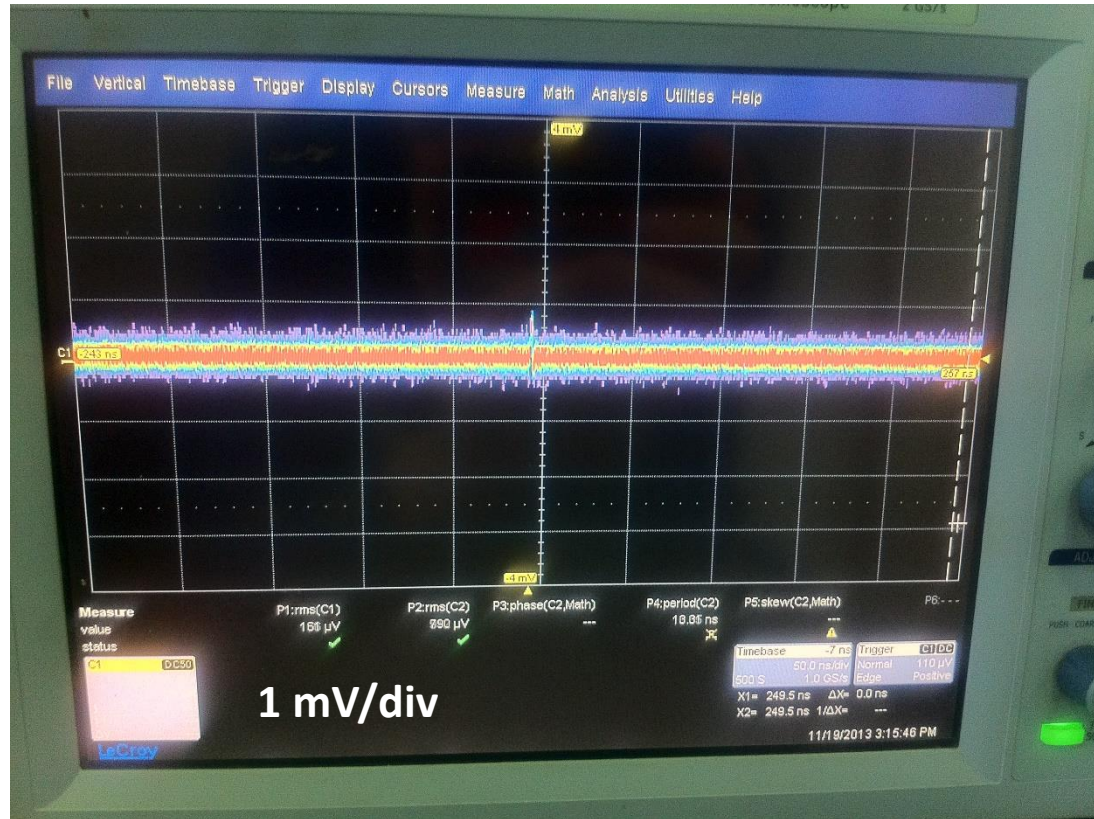
Preliminary results with SiGe amplifier on a diamond detector.

Signals from a Mixed Nuclides alpha source

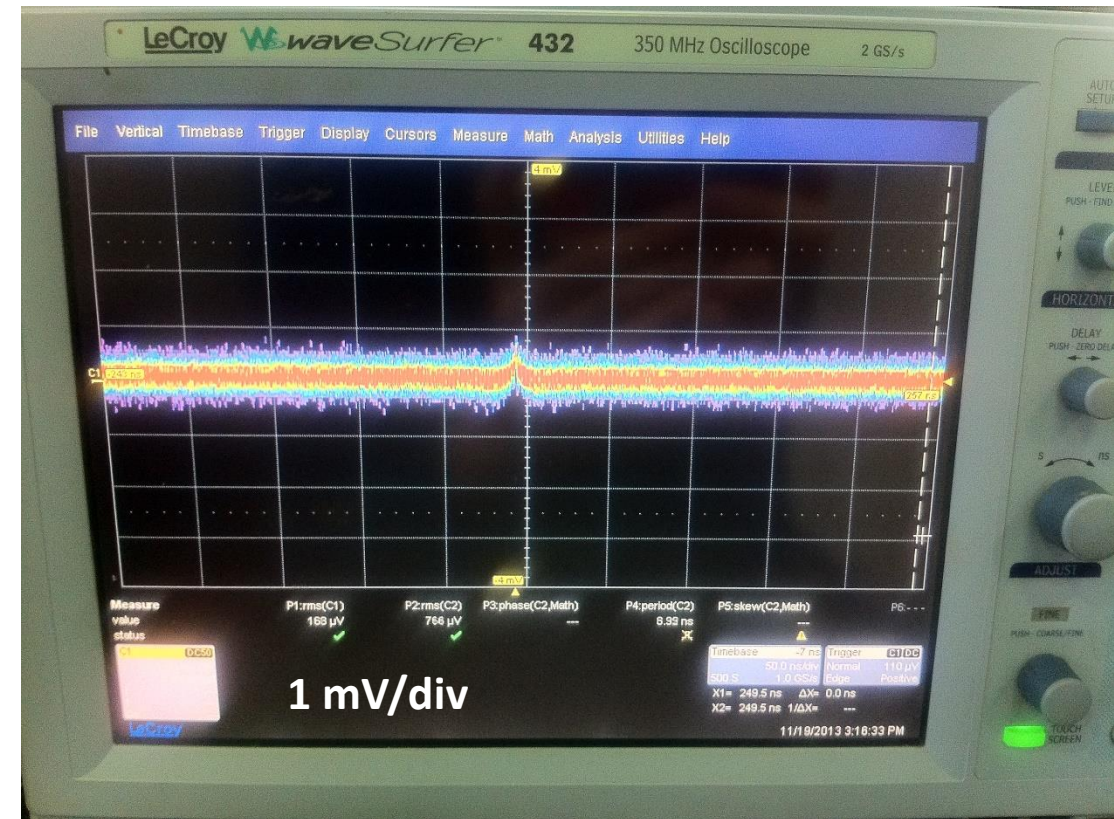


Preliminary results with SiGe amplifier on a diamond detector.

Scope noise



Amplifier+Scope noise



Calibrating with the sources: amplifier noise $\sim 400 e^-$

R. Cardarelli - 02-03/12/2013 - Frascati

Preliminary results with SiGe amplifier on a diamond detector.

Time of flight between a CVD and a 1 mm gap RPC ($\sigma_t \cong 400ps$) with MIPs.

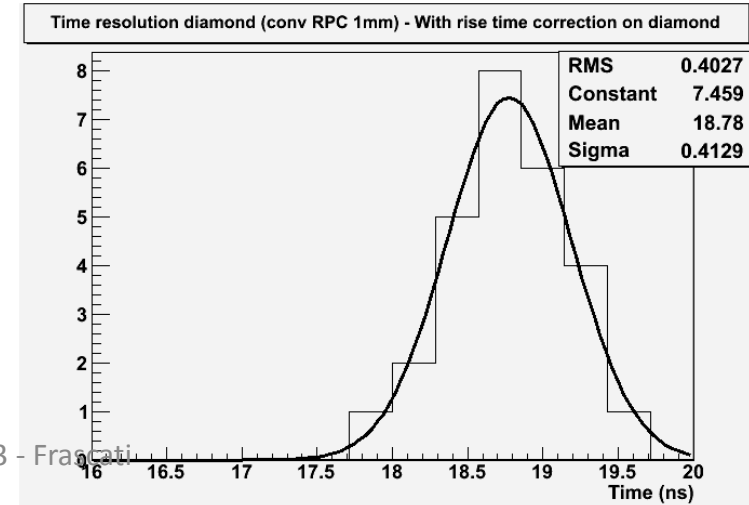
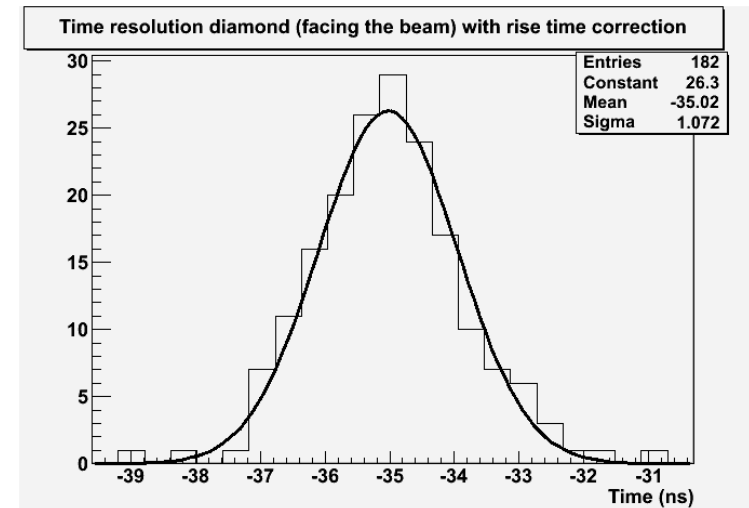
- Assuming $\sigma_{\text{comb}}^2 = \sigma_{\text{Diam}}^2 + \sigma_{\text{RPC}}^2$
- For orthogonal orientation (diamond orthogonal to beam) the overall jitter is dominated by the diamond.

$$\sigma_{\text{Comb}} = 1 \text{ ns}$$

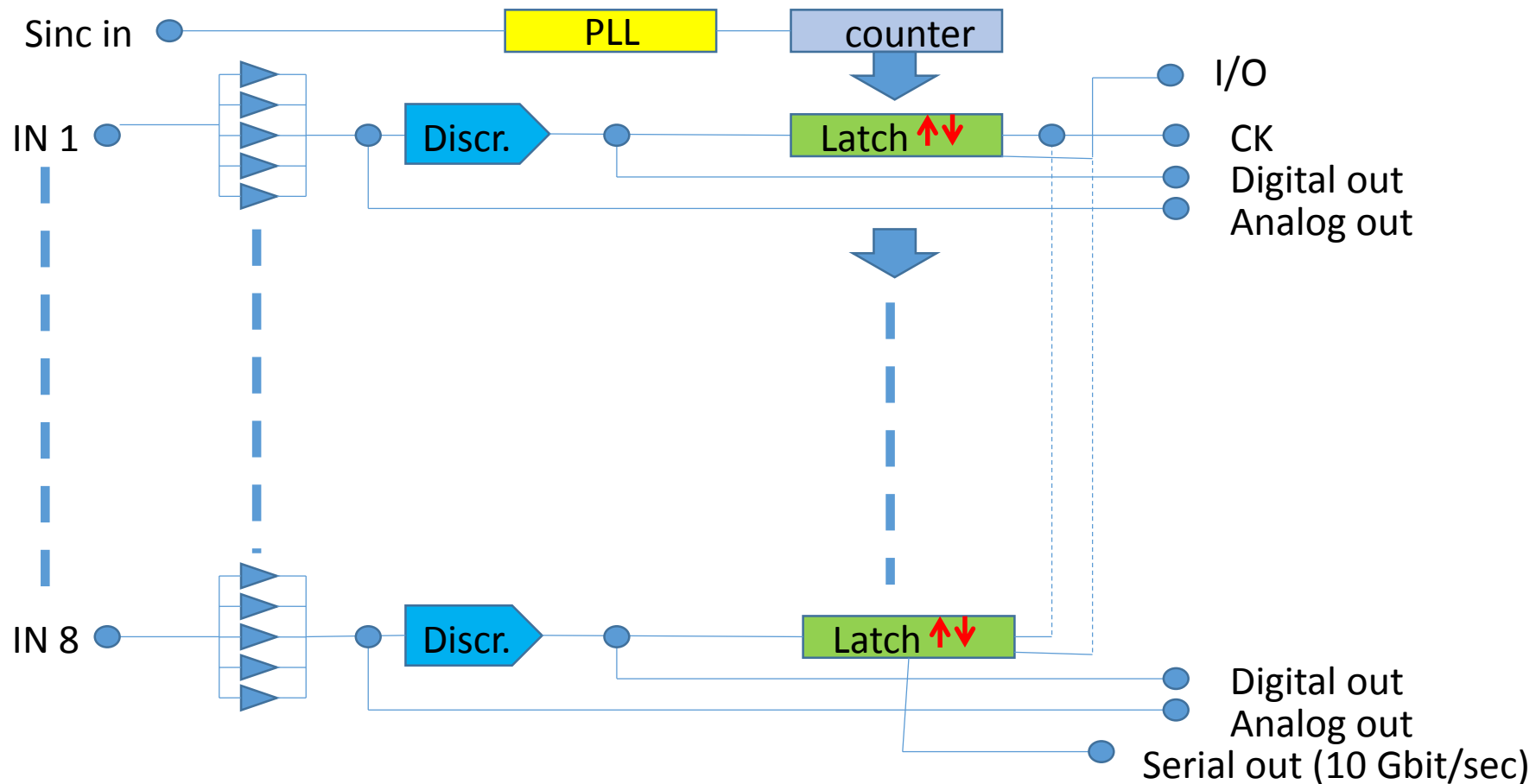
- For parallel orientation the jitter is dominated by the RPC.

$$\sigma_{\text{Comb}} \approx \sigma_{\text{RPC}} = 0.41 \text{ ns}$$




Test beam done at the H8 beam facility at CERN.






Block diagram and performance of a new full custom front-end chip



SiGe requirements for the full custom chip

- Presently this transistor is designed for microwave applications ($> 2\text{ GHz}$).
 Optimization of the transistor for low frequency applications ($\sim 100\text{ MHz}$).
- Sinusoidal signal.
 Pulse signal.
- $1/f$ noise.
 As low as possible.

SiGe requirements for the full custom chip

- Critic application for very high amplification (up to 1000).  High stability.
- Protection from electrostatic discharges.  Up to 2000 V for the gas detector applications.
- Full custom design  Follow the design.

Conclusions

- The prototype of a new fast, ultra low noise preamplifier in SiGe technology has been developed.
- The project of the full custom front end chip is in progress.
- The preliminary tests of SiGe technology at low frequency (pulse signal) offered very promising results.
- On the side of experimental high energy physics, most of the challenges can be faced by introducing SiGe technology in the front end and instrumentation electronics.